

# P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)		
- 30	0.008 at V <sub>GS</sub> = - 10 V	- 75	56 nC		
- 30	0.011 at V <sub>GS</sub> = - 4.5 V	- 65	30 110		

### **FEATURES**

- Halogen-free
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

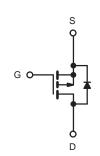


RoHS

## **APPLICATIONS**

- Load Switch
- · Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	- 30	V		
Gate-Source Voltage		$V_{GS}$	± 20		
	T <sub>C</sub> = 25 °C		- 75		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		- 65		
Continuous Diam Current (1) = 130 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	-55 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C		-45 <sup>a, b</sup>		
Pulsed Drain Current		I <sub>DM</sub>	- 200	A	
Continuous Course Davis Diada Courset	T <sub>C</sub> = 25 °C		- 4.1		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	- 2.2 <sup>a, b</sup>		
Avalanche Current		I <sub>AS</sub>	- 75		
Single-Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	280	mJ	
	T <sub>C</sub> = 25 °C		250		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	ь	205	14/	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.7 <sup>a, b</sup>	W	
	T <sub>A</sub> = 70 °C		2.7 <sup>a, b</sup>		
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	20	25		

### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on  $T_C$  = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	$\Delta V_{DS}/T_J$ $I_D = -250 \mu A$		- 34		mV/	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η = - 230 μΑ		5.3		°C	
Gate-Source Threshold Voltage V <sub>GS(th</sub>		$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zana Oata Valtana Busin Ourse	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μА	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
D : 0	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A		0.008		Ω	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 8 A		0.011			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 10 A		28		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			4550		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1455			
Reverse Transfer Capacitance	C <sub>rss</sub>			570			
Tatal Oats Obarra		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		115		20	
Total Gate Charge	Q <sub>g</sub>			56			
Gate-Source Charge	$Q_{gs}$ $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		nC		
Gate-Drain Charge	Q <sub>gd</sub>			22		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			13	25	-	
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		40	70		
Fall Time	t <sub>f</sub>			9	18		
Turn-On Delay Time t <sub>d(on)</sub>				48	80	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160	- - -	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		34	60		
Fall Time	t <sub>f</sub>			19	35		
Drain-Source Body Diode Characteris	tics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 4.1	А	
Pulse Diode Forward Current	I <sub>SM</sub>				- 60		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 3 A, V <sub>GS</sub> = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time				27	45	ns	
Body Diode Reverse Recovery Charge Q		]     10 A dl/dt = 100 A/us T = 25 °C		16	27	nC	
		$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		20	
Reverse Recovery Rise Time	t <sub>b</sub>	]		15		ns	

#### Notes:

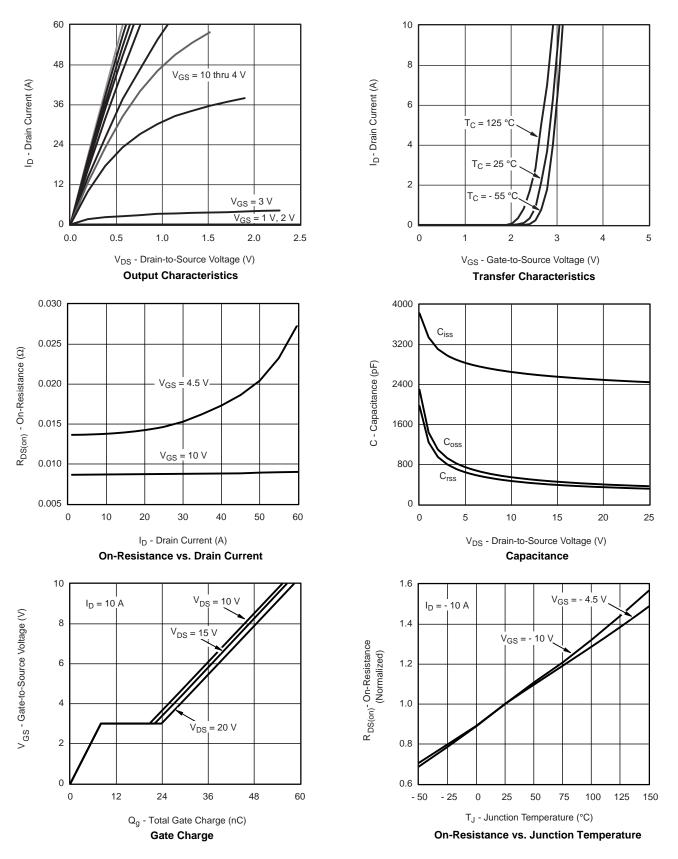
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

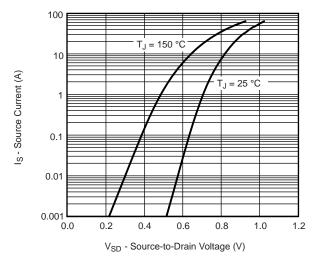


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

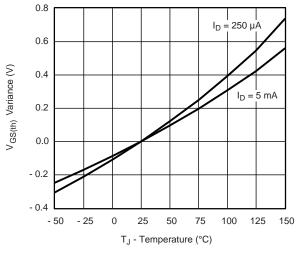




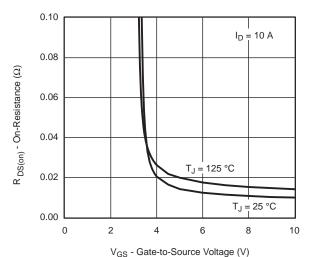
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



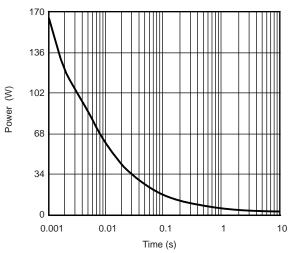
### Source-Drain Diode Forward Voltage



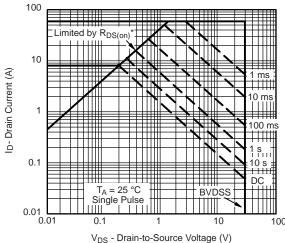
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

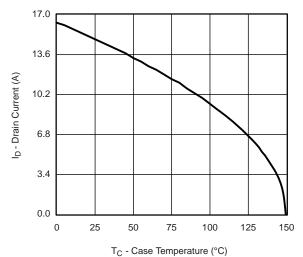


\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

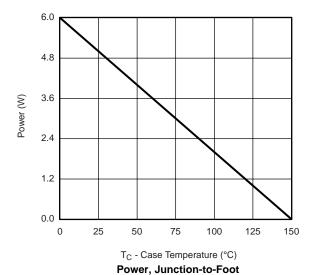
Safe Operating Area

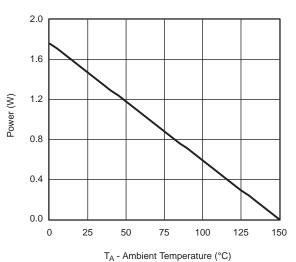


## MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



## **Current Derating\***



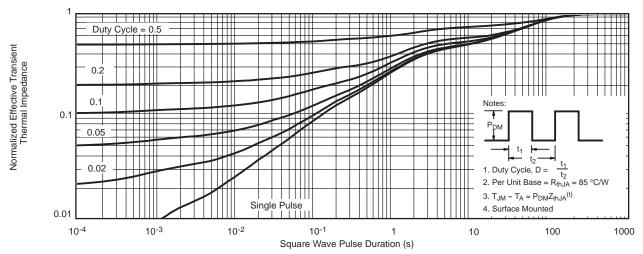


Power Derating, Junction-to-Ambient

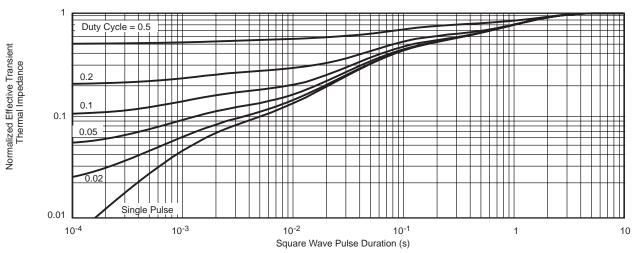
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



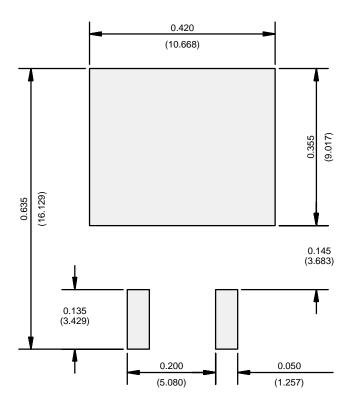
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



## RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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